

ISO652x 通用双通道功能隔离器

1 特性

- 双通道 CMOS 输出功能隔离器
- 50Mbps 数据速率
- 稳健可靠的 SiO₂ 隔离栅 (CMTI 典型值为 $\pm 150\text{kV}/\mu\text{s}$)
- 功能隔离(8-EEU) :
 - 200V_{RMS}、280V_{DC} 工作电压
 - 570V_{RMS}、800V_{DC} 瞬态电压 (60s)
- 功能隔离(8-D) :
 - 450V_{RMS}、637V_{DC} 工作电压
 - 707V_{RMS}、1000V_{DC} 瞬态电压 (60s)
- 采用爬电距离 >2.2mm 的紧凑型 8-REU 封装
- 宽电源电压范围：1.71V 到 1.89V 和 2.25V 到 5.5V
- 1.71V 至 5.5V 电平转换
- 默认输出高电平 (ISO652x) 和低电平 (ISO652xF) 选项
- 宽温度范围：-40°C 至 125°C
- 3.3V、1Mbps 时每通道电流典型值为 1.8mA
- 低传播延迟：3.3V 时为 11ns (典型值)
- 优异的电磁兼容性 (EMC)
 - 系统级 ESD、EFT 和浪涌抗扰度
 - 超低辐射
- 无引线 DFN (8-REU) 封装和窄体 SOIC (8-D) 封装选项

2 应用

- 电源
- 电网、电表
- 电机驱动器
- 工厂自动化
- 楼宇自动化
- 照明
- 电器

3 说明

ISO652x 器件是高性能双通道功能隔离器，适用于需要与非安全应用隔离的成本敏感、空间受限型应用。该隔离栅支持 200V_{RMS}/280V_{DC} 的工作电压，以及 570V_{RMS}/800V_{DC} 的瞬态过压。

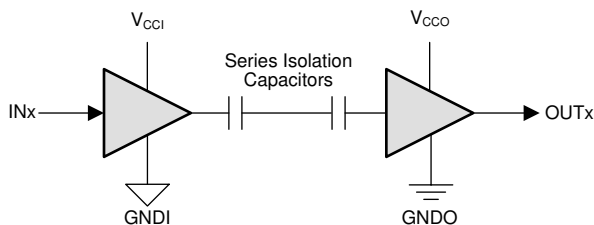
在隔离 CMOS 或 LVCMOS 数字 I/O 的同时，器件可提供高电磁抗扰度、低发射和低功耗特性。每条隔离通道的逻辑输入和输出缓冲器均由 TI 的双电容二氧化硅 (SiO₂) 绝缘栅相隔离。ISO6520 具有 2 个同向隔离通道。ISO6521 具有 2 个隔离通道，每个方向各一个通道。如果输入功率或信号出现损失，不带后缀 F 的器件默认输出高电平，带后缀 F 的器件默认输出低电平。更多详细信息，请参见器件功能模式部分。

这些器件有助于防止 UART、SPI、RS-485、RS-232 和 CAN 等数据总线上的噪声电流损坏敏感电路。得益于芯片设计和布局布线技术，器件的电磁兼容性得到了显著增强，可缓解系统级 ESD 问题并符合辐射标准。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 ⁽²⁾
ISO6520、ISO6520F	DFN (8-REU)	3.0mm x 2.0mm
ISO6521、ISO6521F		
ISO6520、ISO6520F	D (8)	4.9mm x 6.0mm
ISO6521、ISO6521F		

- (1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。
- (2) 封装尺寸 (长 × 宽) 为标称值，并包括引脚 (如适用)。



V_{CCI} = 输入电源，V_{CCO} = 输出电源
GNDI = 输入接地，GNDO = 输出接地

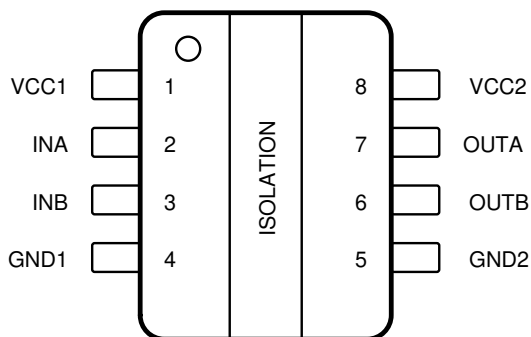
简化原理图



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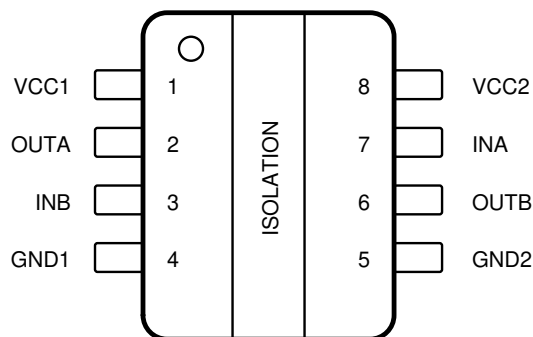
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4 Pin Configuration and Functions



Not to scale

图 4-1. ISO6520 D Package 8-Pin SOIC Top View



Not to scale

图 4-2. ISO6521 D Package 8-Pin SOIC Top View

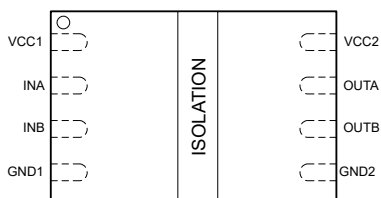


图 4-3. ISO6520 DFN Package 8-Pin REU Top View

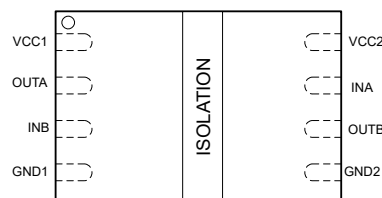


图 4-4. ISO6521 DFN Package 8-Pin REU Top View

表 4-1. Pin Functions

NAME	PIN		TYPE ⁽¹⁾	Description
	ISO6520	ISO6521		
GND1	4	4	-	Ground connection for V _{CC1}
GND2	5	5	-	Ground connection for V _{CC2}
INA	2	7	I	Input, channel A
INB	3	3	I	Input, channel B
OUTA	7	2	O	Output, channel A
OUTB	6	6	O	Output, channel B
V _{CC1}	1	1	P	Power supply, V _{CC1}
V _{CC2}	8	8	P	Power supply, V _{CC2}

(1) I = Input, O = Output, P = Power

5 Specifications

5.1 Absolute Maximum Ratings

See⁽¹⁾

		MIN	MAX	UNIT
Supply Voltage ⁽²⁾	V _{CC1} to GND1	-0.5	6	V
	V _{CC2} to GND2	-0.5	6	
Input/Output Voltage	INx to GNDx	-0.5	V _{CCX} + 0.5 ⁽³⁾	V
	OUTx to GNDx	-0.5	V _{CCX} + 0.5 ⁽³⁾	
Output Current	I _O	-15	15	mA
Temperature	Operating junction temperature, T _J		150	°C
	Storage temperature, T _{stg}	-65	150	°C
Transient Isolation Voltage (REU-8)	AC Voltage, t=60s		570	V _{RMS}
	DC Voltage, t=60s		800	V _{DC}
Transient Isolation Voltage (SOIC-8)	AC Voltage, t=60s		707	V _{RMS}
	DC Voltage, t=60s		1000	V _{DC}

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) All voltage values except differential I/O bus voltages are with respect to the local ground terminal (GND1 or GND2) and are peak voltage values
- (3) Maximum voltage must not exceed 6 V.

5.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±6000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

		TEST CONDITIONS	MIN	NOM	MAX	UNIT
V _{CC1} ⁽¹⁾	Supply Voltage Side 1	V _{CC} = 1.8 V ⁽³⁾	1.71		1.89	V
V _{CC1} ⁽¹⁾	Supply Voltage Side 1	V _{CC} = 2.5 V to 5 V ⁽³⁾	2.25		5.5	V
V _{CC2} ⁽¹⁾	Supply Voltage Side 2	V _{CC} = 1.8 V ⁽³⁾	1.71		1.89	V
V _{CC2} ⁽¹⁾	Supply Voltage Side 2	V _{CC} = 2.5 V to 5 V ⁽³⁾	2.25		5.5	V
V _{CC} (UVLO+)	UVLO threshold when supply voltage is rising			1.53	1.71	V
V _{CC} (UVLO-)	UVLO threshold when supply voltage is falling		1.1	1.41		V
V _{hys} (UVLO)	Supply voltage UVLO hysteresis		0.08	0.13		V
V _{IH}	High level Input voltage		0.7 × V _{CCI} ⁽²⁾		V _{CCI}	V
V _{IL}	Low level Input voltage		0		0.3 × V _{CCI}	V

		TEST CONDITIONS	MIN	NOM	MAX	UNIT
I _{OH}	High level output current	V _{CCO} ⁽²⁾ = 5 V	-4			mA
		V _{CCO} = 3.3 V	-2			mA
		V _{CCO} = 2.5 V	-1			mA
		V _{CCO} = 1.8 V	-1			mA
I _{OL}	Low level output current	V _{CCO} = 5 V			4	mA
		V _{CCO} = 3.3 V			2	mA
		V _{CCO} = 2.5 V			1	mA
		V _{CCO} = 1.8 V			1	mA
DR	Data Rate		0		50	Mbps
T _A	Ambient temperature		-40	25	125	°C
V _{IOWM}	Functional Isolation Working Voltage (REU-8)	AC Voltage (sine wave)			200	V _{RMS}
		DC Voltage			280	V _{DC}
V _{IOWM}	Functional Isolation Working Voltage (SOIC-8)	AC Voltage (sine wave)			450	V _{RMS}
		DC Voltage			637	V _{DC}

(1) V_{CC1} and V_{CC2} can be set independent of one another

(2) V_{CC1} = Input-side V_{CC}; V_{CCO} = Output-side V_{CC}

(3) The channel outputs are in undetermined state when 1.89 V < V_{CC1}, V_{CC2} < 2.25 V and 1.05 V < V_{CC1}, V_{CC2} < 1.71 V

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		ISO652x		UNIT
		DFN (REU-8)	D (SOIC-8)	
		8 PINS	8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	143.4	104.6	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	70.0	48.9	°C/W
R _{θJB}	Junction-to-board thermal resistance	78.3	52.9	°C/W
ψ _{JT}	Junction-to-top characterization parameter	4.2	7.9	°C/W
ψ _{JB}	Junction-to-board characterization parameter	77.7	52.1	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

5.5 Package Characteristics

PARAMETER		TEST CONDITIONS	VALUE	VALUE	UNIT
			8-REU	8-D	
CLR	External clearance ⁽¹⁾	Shortest pin to pin distance through air	>2.2	>4	mm
CPG	External creepage ⁽¹⁾	Shortest pin to pin distance across the package surface	>2.2	>4	mm
CTI	Comparative tracking index	IEC 60112; UL 746A	>400	>400	V
	Material Group	According to IEC 60664-1	II	II	
C _{IO}	Capacitance, input to output ⁽²⁾	V _{IO} = 0.4 × sin (2 π ft), f = 1 MHz	≅0.5	≅0.5	pF
R _{IO}	Resistance, input to output ⁽²⁾	T _A = 25°C	>10 ¹²	>10 ¹²	Ω

(1) Creepage and clearance requirements must be applied according to the specific equipment isolation standards of an application. Care must be taken to maintain the creepage and clearance distance of a board design to verify that the mounting pads of the isolator on the printed-circuit board do not reduce this distance. Creepage and clearance on a printed-circuit board become equal in certain cases. Techniques such as inserting grooves, ribs, or both on a printed circuit board are used to help increase these specifications.

(2) All pins on each side of the barrier tied together creating a two-pin device.

5.6 Electrical Characteristics—5-V Supply

$V_{CC1} = V_{CC2} = 5\text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -4\text{ mA}$; See 图 6-1	$V_{CCO} - 0.4$		V
V_{OL}	Low-level output voltage	$I_{OL} = 4\text{ mA}$; See 图 6-1		0.4	V
$V_{IT+(IN)}$	Rising input switching threshold		$0.7 \times V_{CCI}^{(1)}$		V
$V_{IT-(IN)}$	Falling input switching threshold	$0.3 \times V_{CCI}$			V
$V_{I(HYS)}$	Input threshold voltage hysteresis	$0.1 \times V_{CCI}$			V
I_{IH}	High-level input current	$V_{IH} = V_{CCI}^{(1)}$ at INx		10	μA
I_{IL}	Low-level input current	$V_{IL} = 0\text{ V}$ at INx	-10		μA
CMTI	Common mode transient immunity	$V_I = V_{CC}$ or 0 V , $V_{CM} = 700\text{ V}$; See 图 6-3	100	150	$\text{kV}/\mu\text{s}$
C_i	Input Capacitance ⁽²⁾	$V_I = V_{CC}/2 + 0.4 \times \sin(2\pi ft)$, $f = 2\text{ MHz}$, $V_{CC} = 5\text{ V}$	2.8		pF

(1) V_{CCI} = Input-side V_{CC} ; V_{CCO} = Output-side V_{CC} .

(2) Measured from input pin to same side ground.

5.7 Supply Current Characteristics—5-V Supply

$V_{CC1} = V_{CC2} = 5\text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
ISO6520							
Supply current - DC signal ⁽²⁾	$V_I = V_{CCI}$ ⁽¹⁾ (ISO6520), $V_I = 0$ V (ISO6520 with F suffix)		I_{CC1}		1.1	1.7	mA
			I_{CC2}		1.3	2.2	
	$V_I = 0$ V (ISO6520), $V_I = V_{CC1}$ (ISO6520 with F suffix)		I_{CC1}		3.2	4.6	
			I_{CC2}		1.4	2.3	
Supply current - AC signal ⁽³⁾	All channels switching with square wave clock input; $C_L = 15$ pF	1 Mbps	I_{CC1}		2.1	3.1	
			I_{CC2}		1.5	2.4	
		10 Mbps	I_{CC1}		2.2	3.2	
			I_{CC2}		2.7	3.6	
		50 Mbps	I_{CC1}		2.5	3.6	
			I_{CC2}		7.9	9.5	
ISO6521							
Supply current - DC signal ⁽²⁾	$V_I = V_{CCI}$ ⁽¹⁾ (ISO6521); $V_I = 0$ V (ISO6521 with F suffix)		I_{CC1}, I_{CC2}		1.2	2.2	mA
			I_{CC1}, I_{CC2}		2.3	3.5	
Supply current - AC signal ⁽³⁾	All channels switching with square wave clock input; $C_L = 15$ pF	1 Mbps	I_{CC1}, I_{CC2}		1.9	2.9	
		10 Mbps	I_{CC1}, I_{CC2}		2.5	3.6	
		50 Mbps	I_{CC1}, I_{CC2}		5.2	6.7	

(1) V_{CCI} = Input-side V_{CC}

(2) Supply current valid for $ENx = V_{CCx}$ and $ENx = 0\text{ V}$

(3) Supply current valid for $ENx = V_{CCx}$

5.8 Electrical Characteristics—3.3-V Supply

$V_{CC1} = V_{CC2} = 3.3 \text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$V_{CCO} - 0.2$			V
V_{OL}	Low-level output voltage	0.2			V
$V_{IT+(IN)}$	Rising input switching threshold	$0.7 \times V_{CCI}^{(1)}$			V
$V_{IT-(IN)}$	Falling input switching threshold	$0.3 \times V_{CCI}$			V
$V_{I(HYS)}$	Input threshold voltage hysteresis	$0.1 \times V_{CCI}$			V
I_{IH}	High-level input current	$V_{IH} = V_{CCI}^{(1)}$ at INx			10 μA
I_{IL}	Low-level input current	$V_{IL} = 0 \text{ V}$ at INx			-10 μA
CMTI	Common mode transient immunity	$V_I = V_{CC}$ or 0 V, $V_{CM} = 700 \text{ V}$; See 图 6-3	100	150	kV/ μs
C_i	Input Capacitance ⁽²⁾	$V_I = V_{CC}/2 + 0.4 \times \sin(2\pi ft)$, $f = 2 \text{ MHz}$, $V_{CC} = 3.3 \text{ V}$			2.8 pF

(1) V_{CCI} = Input-side V_{CC} ; V_{CCO} = Output-side V_{CC} .

(2) Measured from input pin to same side ground.

5.9 Supply Current Characteristics—3.3-V Supply

$V_{CC1} = V_{CC2} = 3.3 \text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
ISO6520							
Supply current - DC signal ⁽²⁾	$V_I = V_{CCI}$ ⁽¹⁾ (ISO6520), $V_I = 0$ V (ISO6520 with F suffix)		I_{CC1}		1.1	1.6	mA
			I_{CC2}		1.3	2.2	
	$V_I = 0$ V (ISO6520), $V_I = V_{CC1}$ (ISO6520 with F suffix)		I_{CC1}		3.2	4.5	
			I_{CC2}		1.4	2.3	
Supply current - AC signal ⁽³⁾	All channels switching with square wave clock input; $C_L = 15$ pF	1 Mbps	I_{CC1}		2.1	3.1	
			I_{CC2}		1.4	2.3	
		10 Mbps	I_{CC1}		2.2	3.1	
			I_{CC2}		2.3	3.2	
		50 Mbps	I_{CC1}		2.4	3.4	
			I_{CC2}		6	7.3	
ISO6521							
Supply current - DC signal ⁽²⁾	$V_I = V_{CCI}$ ⁽¹⁾ (ISO6521); $V_I = 0$ V (ISO6521 with F suffix)		I_{CC1}, I_{CC2}		1.2	2.2	mA
			I_{CC1}, I_{CC2}		2.3	3.5	
Supply current - AC signal ⁽³⁾	All channels switching with square wave clock input; $C_L = 15$ pF	1 Mbps	I_{CC1}, I_{CC2}		1.8	2.9	
		10 Mbps	I_{CC1}, I_{CC2}		2.3	3.4	
		50 Mbps	I_{CC1}, I_{CC2}		4.2	5.5	

(1) V_{CCI} = Input-side V_{CC}

(2) Supply current valid for ENx = V_{CCx} and ENx = 0V

(3) Supply current valid for ENx = V_{CCx}

5.10 Electrical Characteristics—2.5-V Supply

$V_{CC1} = V_{CC2} = 2.5 \text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -1\text{mA}$; See 图 6-1		$V_{CCO} - 0.1$	V
V_{OL}	Low-level output voltage	$I_{OL} = 1\text{mA}$; See 图 6-1		0.1	V
$V_{IT+(IN)}$	Rising input switching threshold		$0.7 \times V_{CCI}^{(1)}$		V
$V_{IT-(IN)}$	Falling input switching threshold	$0.3 \times V_{CCI}$			V
$V_{I(HYS)}$	Input threshold voltage hysteresis	$0.1 \times V_{CCI}$			V
I_{IH}	High-level input current	$V_{IH} = V_{CCI}^{(1)}$ at INx		10	μA
I_{IL}	Low-level input current	$V_{IL} = 0 \text{ V}$ at INx	-10		μA
CMTI	Common mode transient immunity	$V_I = V_{CC}$ or 0 V , $V_{CM} = 700\text{V}$; See 图 6-3	100	150	$\text{kV}/\mu\text{s}$
C_i	Input Capacitance ⁽²⁾	$V_I = V_{CC}/2 + 0.4 \times \sin(2\pi ft)$, $f = 2 \text{ MHz}$, $V_{CC} = 2.5 \text{ V}$	2.8		pF

(1) V_{CCI} = Input-side V_{CC} ; V_{CCO} = Output-side V_{CC} .

(2) Measured from input pin to same side ground.

5.11 Supply Current Characteristics—2.5-V Supply

$V_{CC1} = V_{CC2} = 2.5 \text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
ISO6520							
Supply current - DC signal ⁽²⁾	V _I = V _{CCI} ⁽¹⁾ (ISO6520), V _I = 0 V (ISO6520 with F suffix)		I _{CC1}		1.1	1.6	mA
			I _{CC2}		1.3	2.1	
	V _I = 0V (ISO6520), V _I = V _{CC1} (ISO6520 with F suffix)		I _{CC1}		3.1	4.5	
			I _{CC2}		1.4	2.3	
Supply current - AC signal ⁽³⁾	All channels switching with square wave clock input; C _L = 15 pF	1 Mbps	I _{CC1}		2.1	3.1	
			I _{CC2}		1.4	2.3	
		10 Mbps	I _{CC1}		2.1	3.1	
			I _{CC2}		2	2.9	
		50 Mbps	I _{CC1}		2.3	3.3	
			I _{CC2}		4.8	6	
ISO6521							
Supply current - DC signal ⁽²⁾	V _I = V _{CCI} ⁽¹⁾ (ISO6521); V _I = 0 V (ISO6521 with F suffix)		I _{CC1} , I _{CC2}		1.2	2.2	mA
	V _I = 0 V (ISO6521); V _I = V _{CCI} (ISO6521 with F suffix)		I _{CC1} , I _{CC2}		2.3	3.5	
Supply current - AC signal ⁽³⁾	All channels switching with square wave clock input; C _L = 15 pF	1 Mbps	I _{CC1} , I _{CC2}		1.8	2.9	
		10 Mbps	I _{CC1} , I _{CC2}		2.1	3.2	
		50 Mbps	I _{CC1} , I _{CC2}		3.6	4.9	

(1) V_{CCI} = Input-side V_{CC}

(2) Supply current valid for $ENx = V_{CCx}$ and $ENx = 0 \text{ V}$

(3) Supply current valid for $ENx = V_{CCx}$

5.12 Electrical Characteristics—1.8-V Supply

$V_{CC1} = V_{CC2} = 1.8 \text{ V} \pm 5\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -1\text{mA}$; See 图 6-1	$V_{CCO} - 0.1$		V
V_{OL}	Low-level output voltage	$I_{OL} = 1\text{mA}$; See 图 6-1		0.1	V
$V_{IT+(IN)}$	Rising input switching threshold		$0.7 \times V_{CCI}^{(1)}$		V
$V_{IT-(IN)}$	Falling input switching threshold		$0.3 \times V_{CCI}$		V
$V_{I(HYS)}$	Input threshold voltage hysteresis		$0.1 \times V_{CCI}$		V
I_{IH}	High-level input current	$V_{IH} = V_{CCI}^{(1)}$ at INx		10	μA
I_{IL}	Low-level input current	$V_{IL} = 0 \text{ V}$ at INx	-10		μA
CMTI	Common mode transient immunity	$V_I = V_{CC}$ or 0 V , $V_{CM} = 700\text{V}$; See 图 6-3	100	150	$\text{kV}/\mu\text{s}$
C_i	Input Capacitance ⁽²⁾	$V_I = V_{CC}/2 + 0.4 \times \sin(2\pi ft)$, $f = 2 \text{ MHz}$, $V_{CC} = 1.8 \text{ V}$	2.8		pF

(1) V_{CCI} = Input-side V_{CC} ; V_{CCO} = Output-side V_{CC} .

(2) Measured from input pin to same side ground.

5.13 Supply Current Characteristics—1.8-V Supply

$V_{CC1} = V_{CC2} = 1.8 \text{ V} \pm 5\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS		SUPPLY CURRENT	MIN	TYP	MAX	UNIT
ISO6520							
Supply current - DC signal ⁽²⁾	$V_I = V_{CCI}$ ⁽¹⁾ (ISO6520), $V_I = 0$ V (ISO6520 with F suffix)		I_{CC1}		0.8	1.5	mA
			I_{CC2}		1.2	2.1	
	$V_I = 0$ V (ISO6520), $V_I = V_{CC1}$ (ISO6520 with F suffix)		I_{CC1}		2.8	4.3	
			I_{CC2}		1.3	2.3	
Supply current - AC signal ⁽³⁾	All channels switching with square wave clock input; $C_L = 15$ pF	1 Mbps	I_{CC1}		1.8	2.9	
			I_{CC2}		1.3	2.3	
		10 Mbps	I_{CC1}		1.8	2.9	
			I_{CC2}		1.8	2.7	
		50 Mbps	I_{CC1}		2	3.1	
			I_{CC2}		3.8	4.9	
ISO6521							
Supply current - DC signal ⁽²⁾	$V_I = V_{CCI}$ ⁽¹⁾ (ISO6521); $V_I = 0$ V (ISO6521 with F suffix)		I_{CC1}, I_{CC2}		1.1	2.1	mA
	$V_I = 0$ V (ISO6521); $V_I = V_{CC1}$ (ISO6521 with F suffix)		I_{CC1}, I_{CC2}		2.1	3.4	
Supply current - AC signal ⁽³⁾	All channels switching with square wave clock input; $C_L = 15$ pF	1 Mbps	I_{CC1}, I_{CC2}		1.6	2.7	
		10 Mbps	I_{CC1}, I_{CC2}		1.9	3	
		50 Mbps	I_{CC1}, I_{CC2}		3	4.2	

(1) V_{CCI} = Input-side V_{CC}

(2) Supply current valid for $ENx = V_{CCx}$ and $ENx = 0 \text{ V}$

(3) Supply current valid for $ENx = V_{CCx}$

5.14 Switching Characteristics—5-V Supply

$V_{CC1} = V_{CC2} = 5\text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay time	See 图 6-1	11	18	ns
$t_{P(dft)}$	Propagation delay drift		8		ps/°C
t_{UI}	Minimum pulse width	See 图 6-1	20		ns
PWD	Pulse width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $	See 图 6-1	0.2	7	ns
$t_{sk(o)}$	Channel-to-channel output skew time ⁽²⁾	Same direction channels		6	ns
$t_{sk(p-p)}$	Part-to-part skew time ⁽³⁾			6	ns
t_r	Output signal rise time	See 图 6-1	2.6	4.5	ns
t_f	Output signal fall time		2.6	4.5	ns
t_{PU}	Time from UVLO to valid output data			300	μs
t_{DO}	Default output delay time from input power loss	Measured from the time V_{CC} goes below 1.2V. See 图 6-2	0.1	0.3	μs
t_{ie}	Time interval error	$2^{16} - 1$ PRBS data at 50 Mbps	1		ns

(1) Also known as pulse skew.

(2) $t_{sk(o)}$ is the skew between outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical loads.

(3) $t_{sk(pp)}$ is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

5.15 Switching Characteristics—3.3-V Supply

$V_{CC1} = V_{CC2} = 3.3\text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay time	See 图 6-1	11	18	ns
$t_{P(dft)}$	Propagation delay drift		9.2		ps/°C
t_{UI}	Minimum pulse width	See 图 6-1	20		ns
PWD	Pulse width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $	See 图 6-1	0.5	7	ns
$t_{sk(o)}$	Channel-to-channel output skew time ⁽²⁾	Same direction channels		6	ns
$t_{sk(p-p)}$	Part-to-part skew time ⁽³⁾			6	ns
t_r	Output signal rise time	See 图 6-1	1.6	3.2	ns
t_f	Output signal fall time		1.6	3.2	ns
t_{PU}	Time from UVLO to valid output data			300	μs
t_{DO}	Default output delay time from input power loss	Measured from the time V_{CC} goes below 1.2V. See 图 6-2	0.1	0.3	μs
t_{ie}	Time interval error	$2^{16} - 1$ PRBS data at 50 Mbps	1		ns

(1) Also known as pulse skew.

(2) $t_{sk(o)}$ is the skew between outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical loads.

(3) $t_{sk(pp)}$ is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

5.16 Switching Characteristics—2.5-V Supply

$V_{CC1} = V_{CC2} = 2.5 \text{ V} \pm 10\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay time	See 图 6-1	12	20.5	ns
$t_{P(dft)}$	Propagation delay drift		14.3		ps/°C
t_{UI}	Minimum pulse width	See 图 6-1	20		ns
PWD	Pulse width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $	See 图 6-1	0.6	7.1	ns
$t_{sk(o)}$	Channel-to-channel output skew time ⁽²⁾	Same direction channels		6	ns
$t_{sk(p-p)}$	Part-to-part skew time ⁽³⁾			6.1	ns
t_r	Output signal rise time	See 图 6-1	2	4	ns
t_f	Output signal fall time		2	4	ns
t_{PU}	Time from UVLO to valid output data			300	μs
t_{DO}	Default output delay time from input power loss	Measured from the time V_{CC} goes below 1.2V. See 图 6-2	0.1	0.3	μs
t_{ie}	Time interval error	$2^{16} - 1$ PRBS data at 50 Mbps	1		ns

(1) Also known as pulse skew.

(2) $t_{sk(o)}$ is the skew between outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical loads.

(3) $t_{sk(pp)}$ is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

5.17 Switching Characteristics—1.8-V Supply

$V_{CC1} = V_{CC2} = 1.8 \text{ V} \pm 5\%$ (over recommended operating conditions unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay time	See Figure 7-1	15	25.1	ns
$t_{P(dft)}$	Propagation delay drift		15.2		ps/°C
t_{UI}	Minimum pulse width	See Figure 7-1	20		ns
PWD	Pulse width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $	See Figure 7-1	0.7	8.2	ns
$t_{sk(o)}$	Channel-to-channel output skew time ⁽²⁾	Same direction channels		6	ns
$t_{sk(p-p)}$	Part-to-part skew time ⁽³⁾			8.8	ns
t_r	Output signal rise time	See Figure 7-1	2.7	5.3	ns
t_f	Output signal fall time		2.7	5.3	ns
t_{PU}	Time from UVLO to valid output data			300	μs
t_{DO}	Default output delay time from input power loss	Measured from the time V_{CC} goes below 1.2V. See 图 6-2	0.1	0.3	μs
t_{ie}	Time interval error	$2^{16} - 1$ PRBS data at 50 Mbps	1		ns

(1) Also known as pulse skew.

(2) $t_{sk(o)}$ is the skew between outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical loads.

(3) $t_{sk(pp)}$ is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

5.18 Typical Characteristics

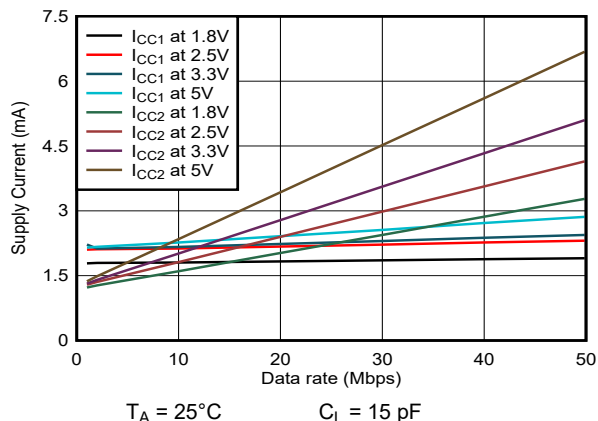


图 5-1. ISO6520 Supply Current vs Data Rate (With 15-pF Load)

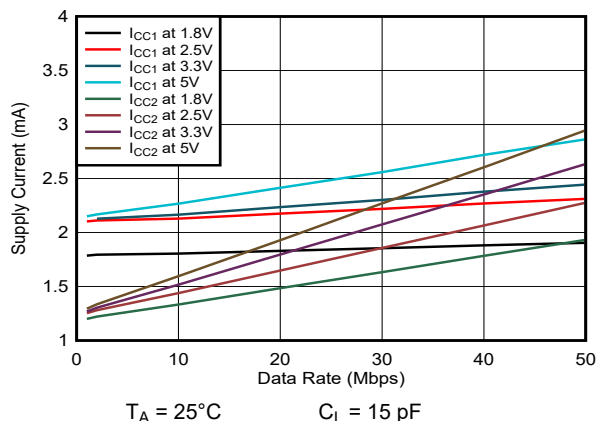


图 5-2. ISO6520 Supply Current vs Data Rate (With No Load)

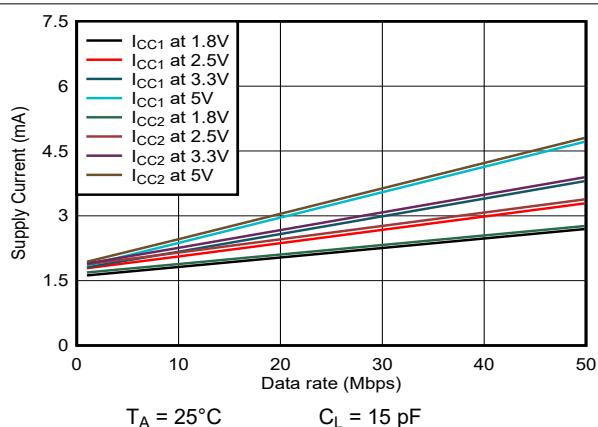


图 5-3. ISO6521 Supply Current vs Data Rate (With 15-pF Load)

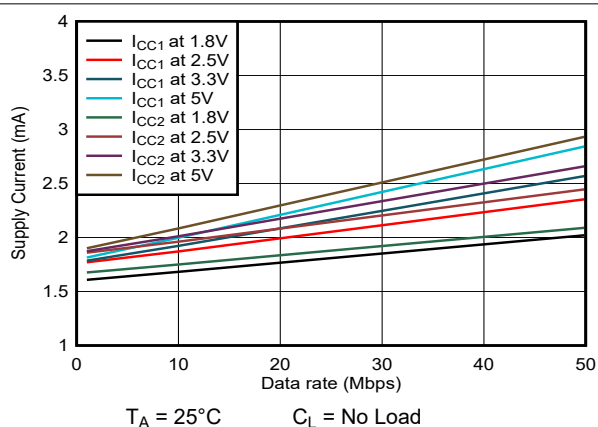


图 5-4. ISO6521 Supply Current vs Data Rate (With No Load)

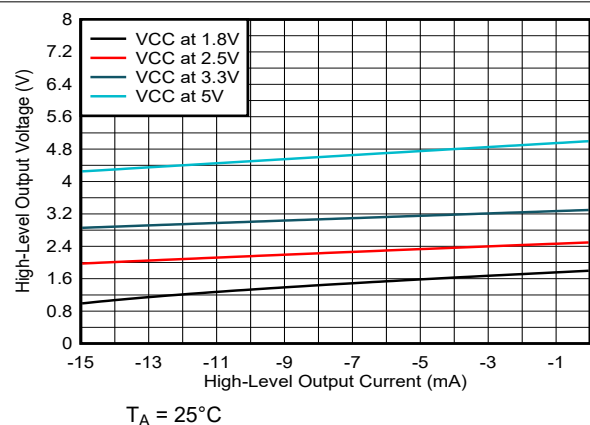


图 5-5. High-Level Output Voltage vs High-level Output Current

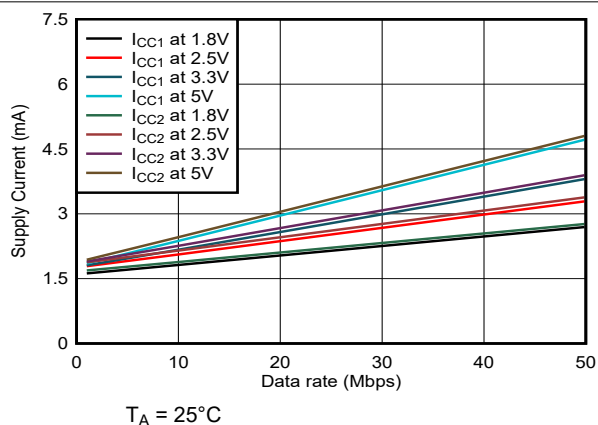


图 5-6. Low-Level Output Voltage vs Low-Level Output Current

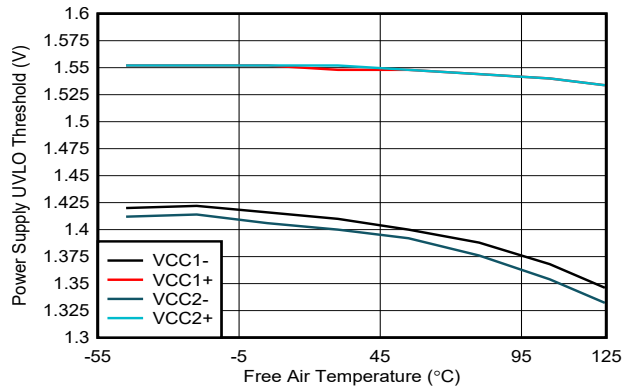


图 5-7. Power Supply Undervoltage Threshold vs Free-Air Temperature

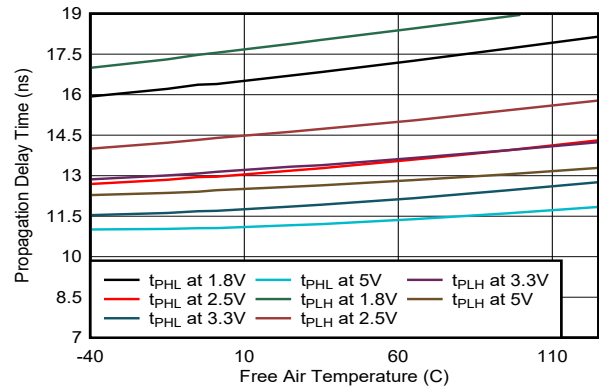
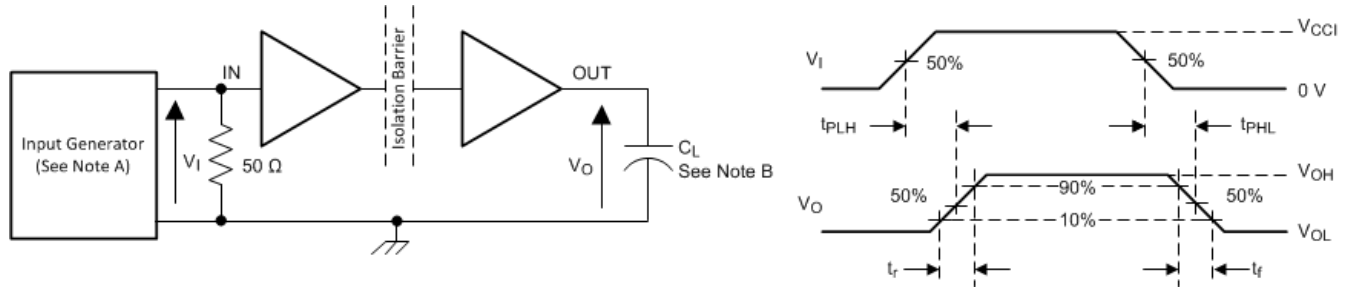


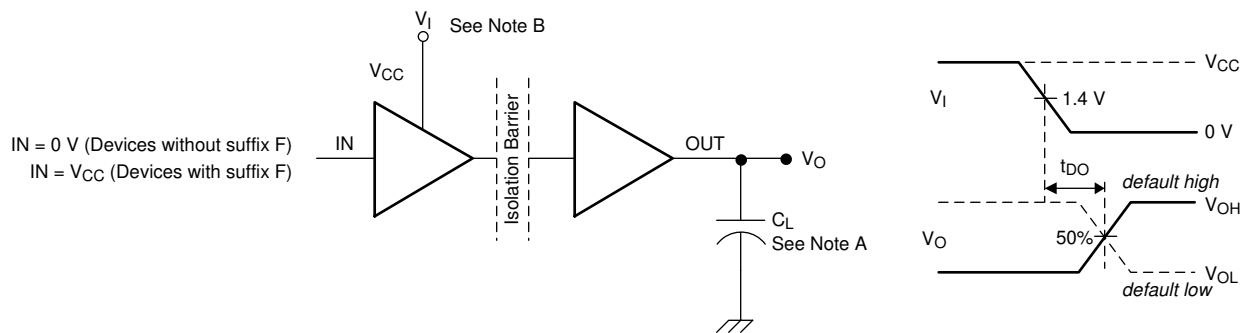
图 5-8. Propagation Delay Time vs Free-Air Temperature

6 Parameter Measurement Information



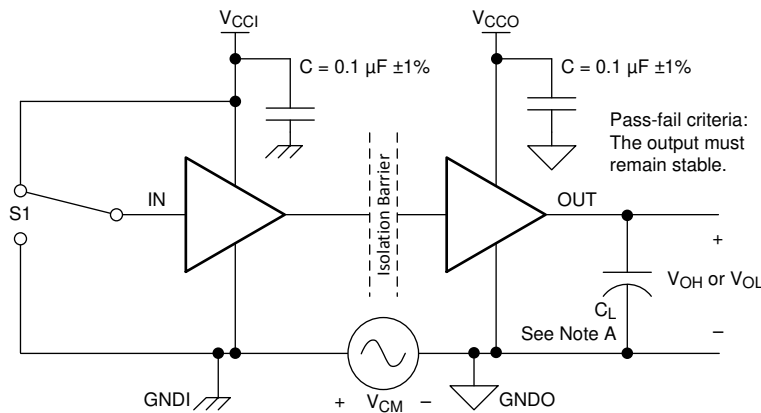
- A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 50 \text{ kHz}$, 50% duty cycle, $t_r \leq 3 \text{ ns}$, $t_f \leq 3 \text{ ns}$, $Z_O = 50 \Omega$. At the input, 50Ω resistor is required to terminate Input Generator signal. The 50Ω resistor is not needed in the actual application.
- B. $C_L = 15 \text{ pF}$ and includes instrumentation and fixture capacitance within $\pm 20\%$.

图 6-1. Switching Characteristics Test Circuit and Voltage Waveforms



- A. $C_L = 15 \text{ pF}$ and includes instrumentation and fixture capacitance within $\pm 20\%$.
- B. Power Supply Ramp Rate = 10 mV/ns

图 6-2. Default Output Delay Time Test Circuit and Voltage Waveforms



- A. $C_L = 15 \text{ pF}$ and includes instrumentation and fixture capacitance within $\pm 20\%$.

图 6-3. Common-Mode Transient Immunity Test Circuit

7 Detailed Description

7.1 Overview

The ISO652x family of devices has an ON-OFF keying (OOK) modulation scheme to transmit the digital data across a silicon dioxide based isolation barrier. The transmitter sends a high frequency carrier across the barrier to represent one digital state and sends no signal to represent the other digital state. The receiver demodulates the signal after advanced signal conditioning and produces the output through a buffer stage. These devices also incorporate advanced circuit techniques to maximize the CMTI performance and minimize the radiated emissions due the high frequency carrier and IO buffer switching. The conceptual block diagram of a digital capacitive isolator, 图 7-1, shows a functional block diagram of a typical channel.

7.2 Functional Block Diagram

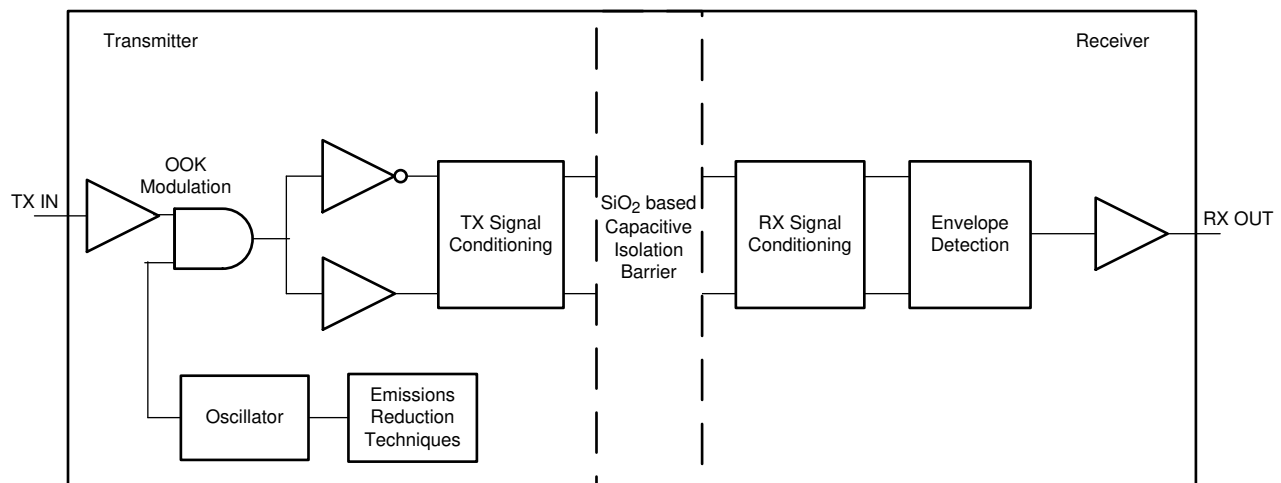


图 7-1. Conceptual Block Diagram of a Digital Capacitive Isolator

图 7-2 shows a conceptual detail of how the OOK scheme works.

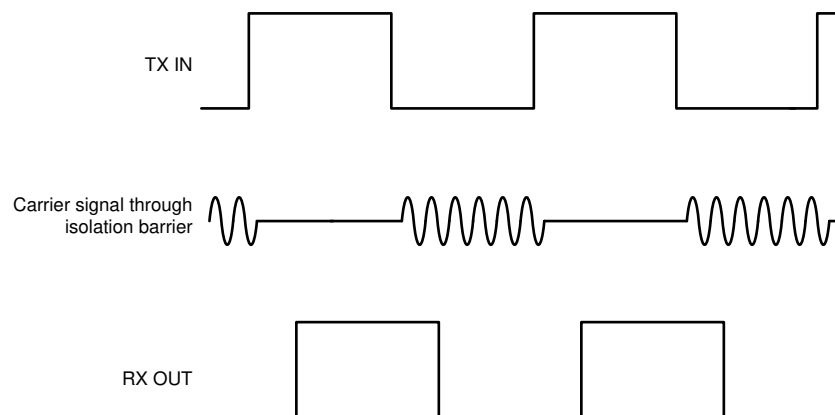


图 7-2. On-Off Keying (OOK) Based Modulation Scheme

7.3 Feature Description

family of devices is available in two channel configurations and default output state options to enable a variety of application uses. lists the device features of the devices.

表 7-1. Device Features

PART NUMBER	MAXIMUM DATA RATE	CHANNEL DIRECTION	DEFAULT OUTPUT STATE	PACKAGE
ISO6520	50 Mbps	2 Forward, 0 Reverse	High	REU-8
ISO6520F	50 Mbps	2 Forward, 0 Reverse	Low	REU-8
ISO6521	50 Mbps	1 Forward, 1 Reverse	High	REU-8
ISO6521F	50 Mbps	1 Forward, 1 Reverse	Low	REU-8

7.4 Device Functional Modes

表 7-2 lists the functional modes for the devices.

表 7-2. Function Table

$V_{CCI}^{(1)}$	V_{CCO}	INPUT (INx) ⁽²⁾	OUTPUT (OUTx)	COMMENTS
PU	PU	H	H	Normal Operation: A channel output assumes the logic state of the input.
		L	L	
		Open	Default	Default mode: When INx is open, the corresponding channel output goes to the default logic state. The default is <i>High</i> for and <i>Low</i> for with F suffix.
PD	PU	X	Default	Default mode: When V_{CCI} is unpowered, a channel output assumes the logic state based on the selected default option. The default is <i>High</i> for and <i>Low</i> for with F suffix. When V_{CCI} transitions from unpowered to powered-up, a channel output assumes the logic state of the input. When V_{CCI} transitions from powered-up to unpowered, channel output assumes the selected default state.
X	PD	X	Undetermined	When V_{CCO} is unpowered, a channel output is undetermined ⁽³⁾ . When V_{CCO} transitions from unpowered to powered-up, a channel output assumes the logic state of the input

(1) V_{CCI} = Input-side V_{CC} ; V_{CCO} = Output-side V_{CC} ; PU = Powered up ($V_{CC} \geq 1.71V$); PD = Powered down ($V_{CC} \leq 1.05V$); X = Irrelevant; H = High level; L = Low level

(2) A strongly driven input signal can weakly power the floating V_{CC} via an internal protection diode and cause undetermined output.

(3) The outputs are in undetermined state when $1.89V < V_{CCI}$, $V_{CCO} < 2.25V$ and $1.05V < V_{CCI}$, $V_{CCO} < 1.71V$

7.4.1 Device I/O Schematics

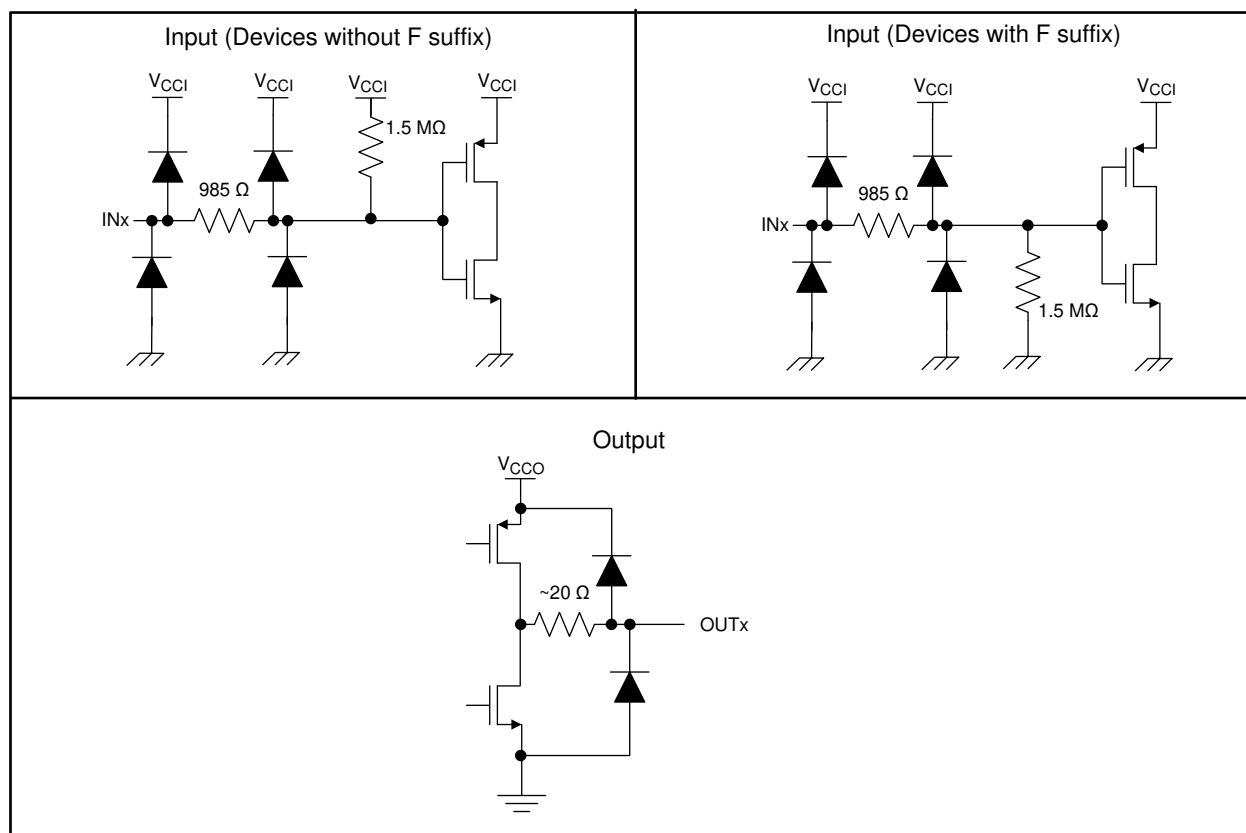


图 7-3. Device I/O Schematics

8.2.1 Design Requirements

To design with these devices, use the parameters listed in [表 8-1](#).

表 8-1. Design Parameters

PARAMETER	VALUE
Supply voltage, V_{CC1} and V_{CC2}	1.71 V to 1.89 V and 2.25 V to 5.5 V
Decoupling capacitor between V_{CC1} and GND1	0.1 μ F
Decoupling capacitor from V_{CC2} and GND2	0.1 μ F

9 Power Supply Recommendations

To provide reliable operation at data rates and supply voltages, a 0.1- μ F bypass capacitor is recommended at the input and output supply pins (V_{CC1} and V_{CC2}). The capacitors must be placed as close to the supply pins as possible. If only a single primary-side power supply is available in an application, isolated power can be generated for the secondary-side with the help of a transformer driver. For industrial applications, please use Texas Instruments' [SN6501](#) or [SN6505B](#). For such applications, detailed power supply design and transformer selection recommendations are available in [SN6501 Transformer Drivers for Isolated Power Supplies](#) or [SN6505B-Q1 Low-noise, 1-A Transformer Drivers for Isolated Power Supplies](#).

10 Layout

10.1 Layout Guidelines

A minimum of two layers is required to accomplish a cost optimized and low EMI PCB design. To further improve EMI, a four layer board can be used. Layer stacking for a four layer board must be in the following order (top-to-bottom): high-speed signal layer, ground plane, power plane and low-frequency signal layer.

- Routing the high-speed traces on the top layer avoids the use of vias (and the introduction of the inductances) and allows for clean interconnects between the isolator and the transmitter and receiver circuits of the data link.
- Placing a solid ground plane next to the high-speed signal layer establishes controlled impedance for transmission line interconnects and provides an excellent low-inductance path for the return current flow.
- Placing the power plane next to the ground plane creates additional high-frequency bypass capacitance of approximately 100 pF/in².
- Routing the slower speed control signals on the bottom layer allows for greater flexibility as these signal links usually have margin to tolerate discontinuities such as vias.
- Bypass the VCC pin to ground with a low-ESR ceramic bypass capacitor. The typical recommended bypass capacitance is 0.1 μ F when using a ceramic capacitor with an X5R- or X7R-rated dielectric. The capacitor must be placed as close to the VCC pin as possible in the PCB layout and on the same layer. The capacitor must have a voltage rating greater than the VCC voltage level.

If an additional supply voltage plane or signal layer is needed, add a second power or ground plane system to the stack to keep the planes symmetrical. This design makes the stack mechanically stable and prevents warping. Also the power and ground plane of each power system can be placed closer together, thus increasing the high-frequency bypass capacitance significantly.

For detailed layout recommendations, refer to the [Digital Isolator Design Guide](#).

10.1.1 PCB Material

For digital circuit boards operating at less than 150 Mbps, (or rise and fall times greater than 1 ns), and trace lengths of up to 10 inches, use standard FR-4 UL94V-0 printed circuit board. This PCB is preferred over cheaper alternatives because of lower dielectric losses at high frequencies, less moisture absorption, greater strength and stiffness, and the self-extinguishing flammability-characteristics.

10.2 Layout Example

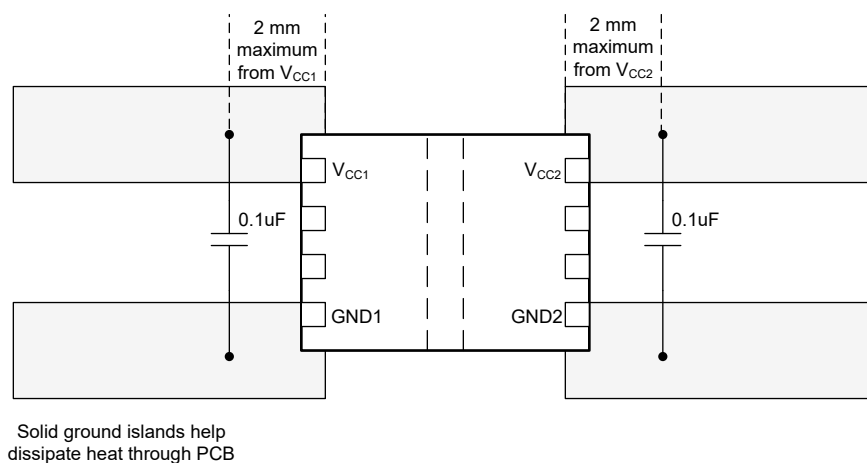


图 10-1. Layout Example

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [Isolation Glossary](#), application note
- Texas Instruments, [SN6501 Transformer Driver for Isolated Power Supplies](#), data sheet
- Texas Instruments, [SN6505x Low-Noise 1-A Transformer Drivers for Isolated Power Supplies](#), data sheet
- Texas Instruments, [SN6507 Low-Emissions, 36-V Push-Pull Transformer Driver with Duty Cycle Control for Isolated Power Supplies](#), data sheet
- Texas Instruments, [LMG341xR070 600-V 70-mΩ GaN with Integrated Driver and Protection](#), data sheet

11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的[使用条款](#)。

11.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

11.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.6 术语表

TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

12 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision A (December 2023) to Revision B (April 2024)	Page
• 更新了整个文档中的表格、图和交叉参考的编号格式.....	1
• 在整个文档中添加了有关 ISO6521F 型号的信息.....	1

Changes from Revision * (August 2023) to Revision A (December 2023)	Page
• 将器件状态更新为“量产数据”	1
• Updated Typical Application Diagram.....	18

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ISO6520DR	Active	Production	SOIC (D) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	6520
ISO6520FDR	Active	Production	SOIC (D) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	6520F
ISO6520FREUR	Active	Production	VSON (REU) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	6520F
ISO6520REUR	Active	Production	VSON (REU) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	6520
ISO6521DR	Active	Production	SOIC (D) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	6521
ISO6521FDR	Active	Production	SOIC (D) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	6521F
ISO6521FREUR	Active	Production	VSON (REU) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	6521F
ISO6521REUR	Active	Production	VSON (REU) 8	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	6521

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF ISO6520, ISO6521 :

- Automotive : [ISO6520-Q1](#), [ISO6521-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO6520DR	SOIC	D	8	3000	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO6520FDR	SOIC	D	8	3000	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO6520FREUR	VSON	REU	8	3000	180.0	12.4	2.3	3.3	1.2	4.0	12.0	Q2
ISO6520REUR	VSON	REU	8	3000	180.0	12.4	2.3	3.3	1.2	4.0	12.0	Q2
ISO6521DR	SOIC	D	8	3000	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO6521FDR	SOIC	D	8	3000	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO6521FREUR	VSON	REU	8	3000	180.0	12.4	2.3	3.3	1.2	4.0	12.0	Q2
ISO6521REUR	VSON	REU	8	3000	180.0	12.4	2.3	3.3	1.2	4.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ISO6520DR	SOIC	D	8	3000	353.0	353.0	32.0
ISO6520FDR	SOIC	D	8	3000	353.0	353.0	32.0
ISO6520FREUR	VSON	REU	8	3000	210.0	185.0	35.0
ISO6520REUR	VSON	REU	8	3000	210.0	185.0	35.0
ISO6521DR	SOIC	D	8	3000	353.0	353.0	32.0
ISO6521FDR	SOIC	D	8	3000	353.0	353.0	32.0
ISO6521FREUR	VSON	REU	8	3000	210.0	185.0	35.0
ISO6521REUR	VSON	REU	8	3000	210.0	185.0	35.0

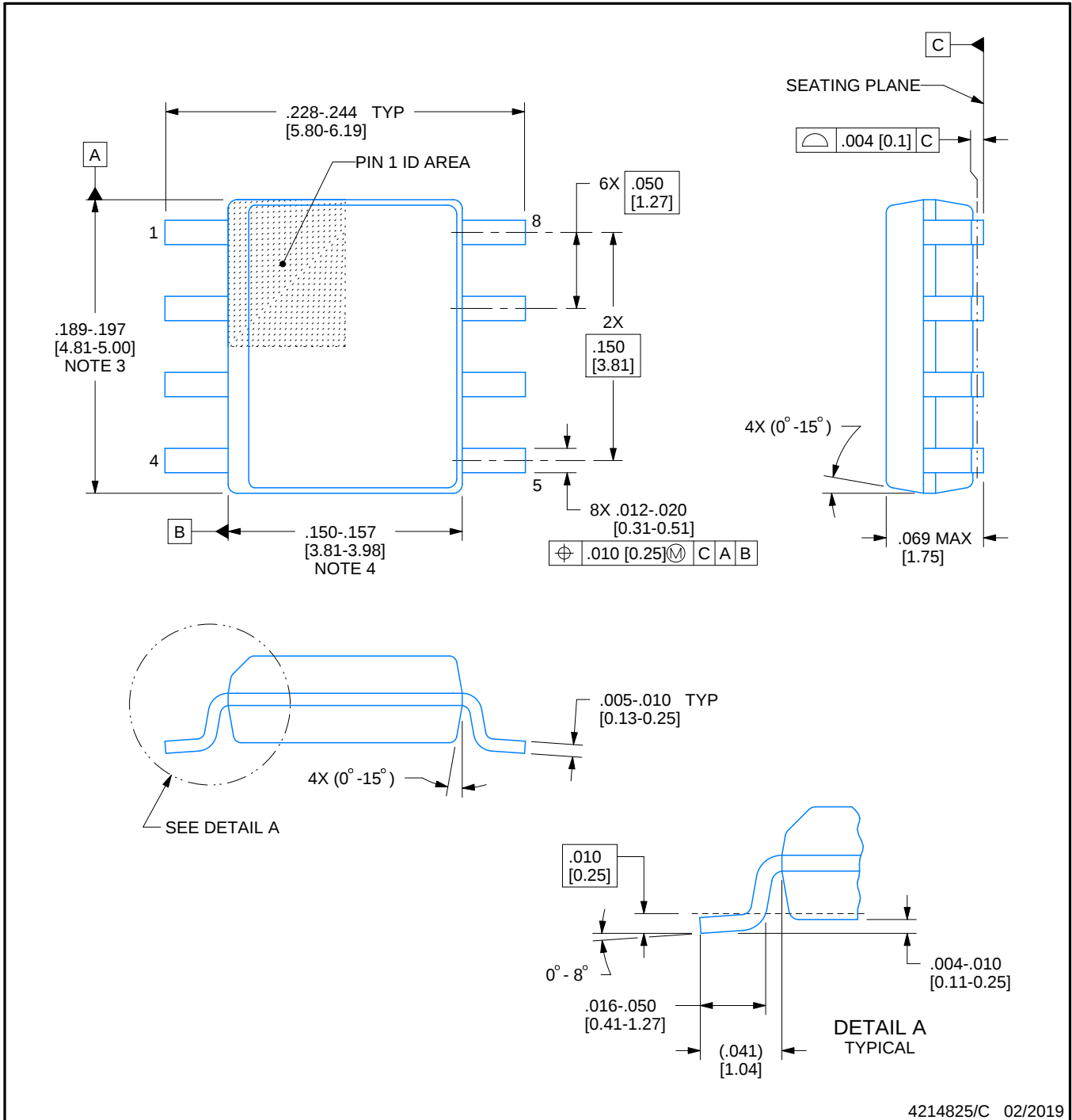


D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

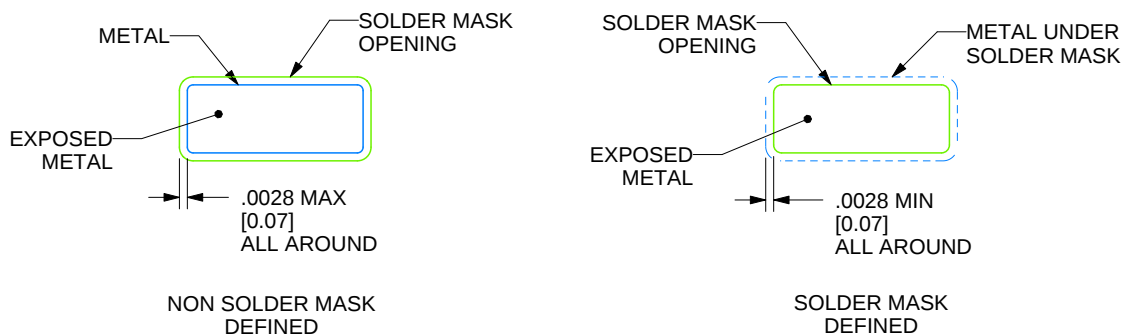
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



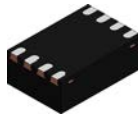
SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

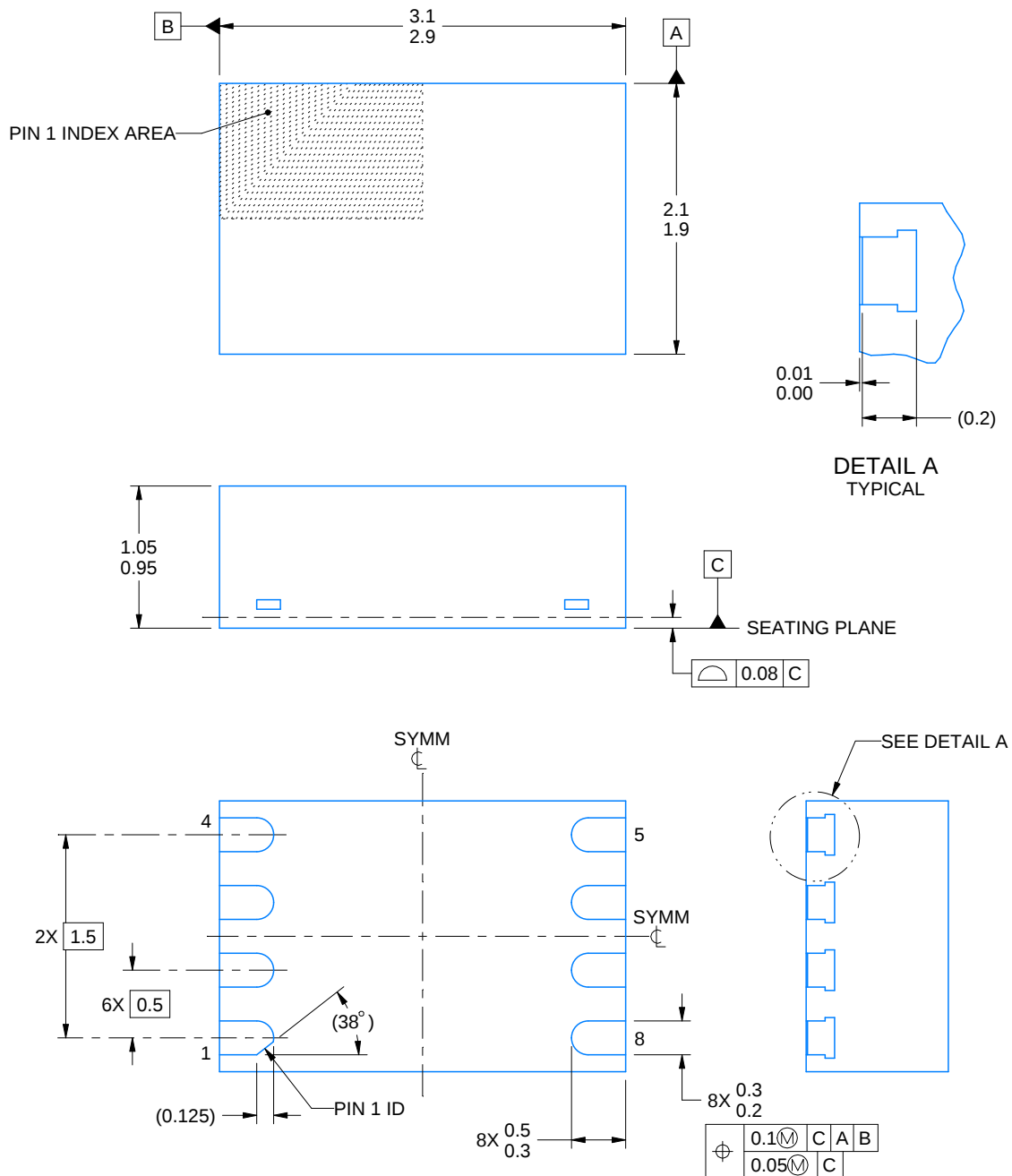
REU0008A



PACKAGE OUTLINE

VSON - 1.05 mm max height

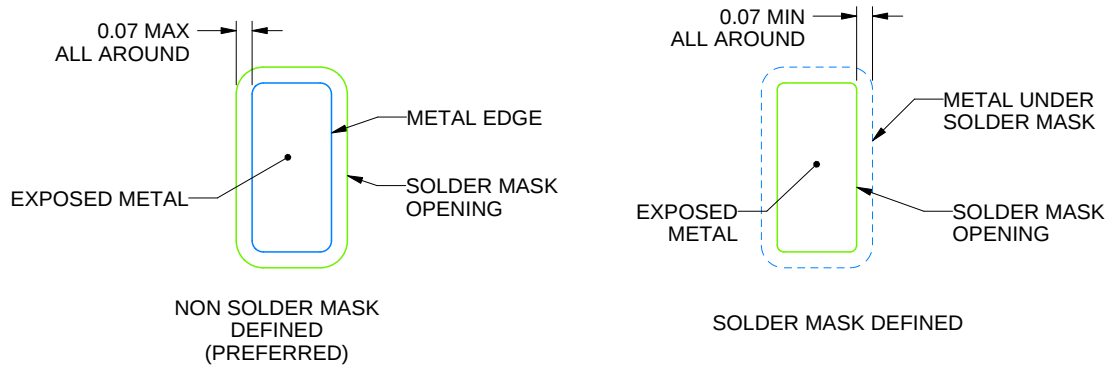
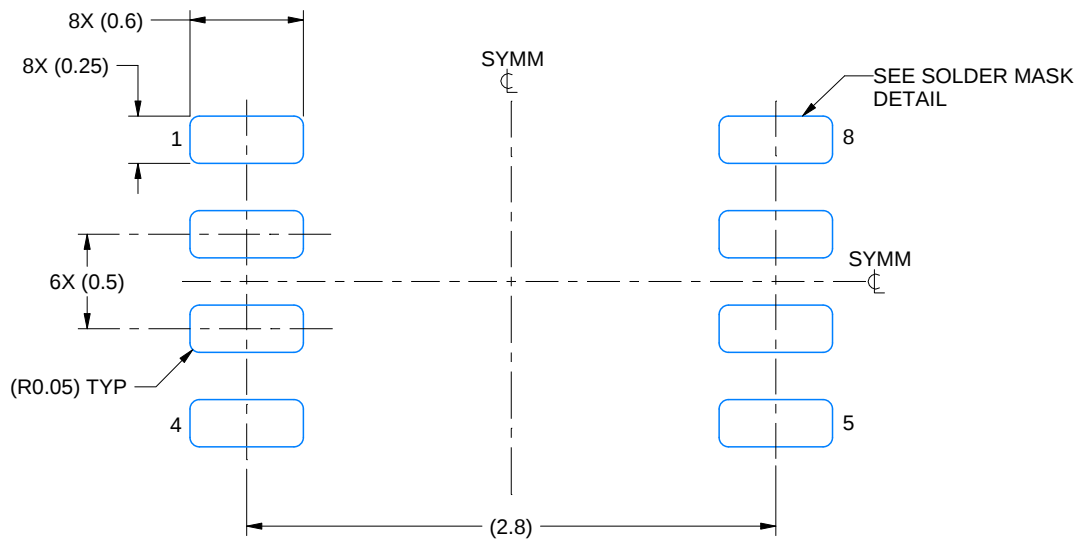
PLASTIC SMALL OUTLINE - NO LEAD



4229400/A 02/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

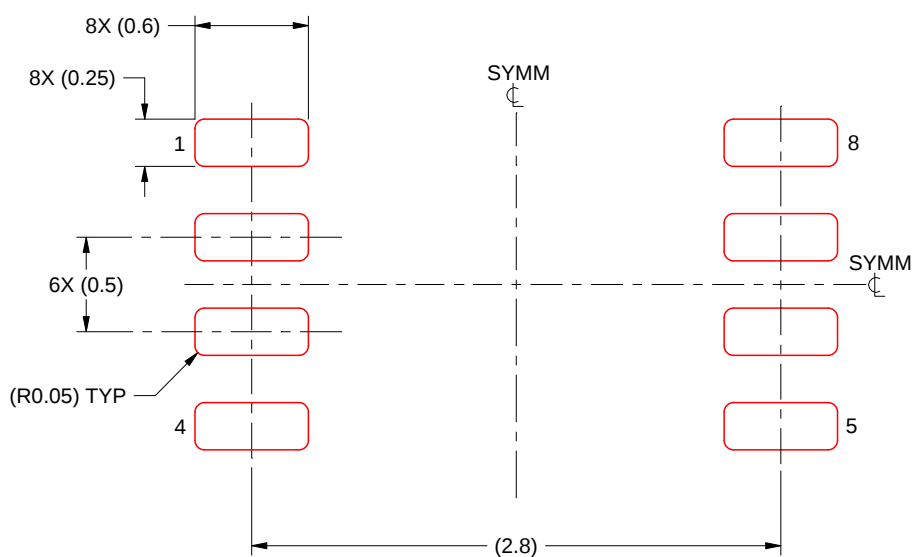


EXAMPLE STENCIL DESIGN

REU0008A

VSON - 1.05 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 25X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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